

EV Group Hybrid Bonding and NIL Solutions Highlighted at SEMICON Taiwan – September 1, 2023

semiconductor  
packaging news

We search for industry news, so you don't need to.

HOME PAPERS SUBSCRIBE TRANSLATE

September 1, 2023

Need To Share Data Widens In IC Manufacturing

The demand for data sharing in IC manufacturing is expanding rapidly. As technology advances, collaboration and information exchange between various stakeholders become increasingly crucial. Manufacturers, designers, and foundries must seamlessly share data to ensure efficient production processes, quicker problem resolution, ...

Semiconductor Engineering



SUMMARY

Large Capacity Plasma Treatment System - FlexTRAK-SHS

9.6-liter plasma process chamber handles larger, or more, strips increasing throughput and productivity for electronics/semiconductor packaging.

MARCH | Nordson Electronics Solutions



BGA Component Rework Simplified

When you're confronted with tough BGA rework, who do you turn to? Discover the #1 resource used by military contractors. We have solutions for all your BGA rework and repair needs.

Circuit Technology Center



SUMMARY

Worldwide Smartphone Shipments Forecast to Reach Lowest Volume in a Decade While iOS Share Climbs to Record Levels in 2023

The worldwide smartphone market has witnessed remarkable growth, as global shipments reached a new high in ...

IDC

SUMMARY

Heterogeneous IC Packaging: Optimizing Performance And Cost

The choice of packaging technology is influenced by the communication interface between chiplets.

Technical Paper

DOWNLOAD

Performance & Efficiency Cores For Servers

A new approach to server efficiency and performance emerges as researchers focus on creating specialized cores ...

Semiconductor Engineering

SUMMARY

Technical Papers

- 3D Sensing Solutions
- Critical Cleaning Requirements to Overcome Advanced Packaging and Refluxing Challenges
- Reliably Reinforce BGAs While Minimizing Stress on Solder Joints
- Series A: Electrical Insulation of Al2O3-Coated Bonding Wire
- Production Testing Of Discrete Power Products
- Essential Inspection Requirements in the Era of Convergence
- Photosensitive Permanent Bonding Material Designed for Polymer/Metal Hybrid Bonding Applications

Microelectronics Assembly & Packaging

Flip Chip, Thermocompression, Wire Bonding, Encapsulation. Applications: RF, mmWave, Military, LiDAR, Medical, Photonics, MEMS.

AmTECH Microelectronics



SAWA SC-BM500E Automatic Stencil Cleaner

Ultrasonic combined with spray cleaning provides an excellent solution for all kinds of applications including wafer bump and electroform stencils.

Seika



Introducing ASE's Integrated Design Ecosystem™ (IDE)

ASE's IDE is a collaborative design toolset optimized to systematically boost advanced package architecture across its VIPack™ platform.

ASE



Today's Sponsor



Test Your Knowledge

What line on a map connects all points of the same elevation?

See answer below.

Hybrid Bonding Platform Solution

The automated SUSS XBS300 Hybrid Bonding Platform allows for state-of-the-art hybrid bonding at the highest accuracy on 200 and 300mm substrates.

SUSS MicroTec



Press Releases

EV Group Hybrid Bonding and NIL Solutions Highlighted at SEMICON Taiwan

EV Group (EVG) announced that new developments in 3D/heterogeneous integration and augmented reality (AR) waveguide manufacturing enabled by its advanced wafer ...

EV Group

Brewer Science unveils advanced packaging solutions at SEMICON Taiwan 2023

Brewer Science, Inc., will present new developments in temporary and permanent bonding material technologies for advanced packaging this week at Asia's two premier ...

Brewer Science, Inc

Vietnam Business Summit 2023: Paving the Way for Vietnam's Semiconductor Industry Growth

Key semiconductor industry players and stakeholders including partners, government agencies, and academia will gather September 28-29 in Hanoi for the Vietnam Business ...

SEMI

From Silicon to Sustainability!

Electronics Goes Green 2024+, the world's premier event on sustainability & electronics, takes place in Berlin in June 2024. Abstract submission extended to Dec 6.

Fraunhofer IZM



**[EUV pod supplier alliance welcomed by key customer](#)**

Gudeng Precision Industrial Co, a key supplier of extreme ultraviolet (EUV) pods to Taiwan Semiconductor Manufacturing ...

Taipei Times

SUMMARY

**[Nvidia partner expects sales to double](#)**

Quanta Cloud Technology (QCT), Nvidia Corp's partner, projects a doubling of sales for its AI servers ...

Taipei Times

SUMMARY

**[China exports of gallium and germanium surged before restrictions took effect in August, report shows](#)**

China's exports of gallium and germanium experienced a significant surge as new restrictions came into effect ...

South China Morning Post

SUMMARY

**finetech**  
Process Development Services

Class 1000 (ISO 6) clean room • High precision die bonders (0.3 μm, 0.5 μm)  
• Expertise you can rely on to fast-track from prototype to production  
[www.finetechusa.com](http://www.finetechusa.com)

**WX3000™**  
Metrology and Inspection Systems for Wafer-Level & Advanced Packaging

**NEW**

**CYBEROPTICS**  
LEARN MORE >>>

Is there a way to find critical defects in semiconductors faster?

**comet**  
cycles

**[Apple reportedly tests 3D printing to manufacture the new Apple Watch](#)**

Apple is reportedly exploring the integration of 3D printing technology into its manufacturing process for the ...

CNBC

SUMMARY

**[Dell, HP and Apple supplier Foxconn apply to make laptops in India under US\\$2.1 billion incentive plan](#)**

Major tech companies Dell, HP, and Apple supplier Foxconn are set to manufacture laptops in India ...

South China Morning Post

SUMMARY

**[Huawei's new phone juices Chinese chip stocks](#)**

Huawei's latest smartphone launch has ignited a surge in Chinese chip stocks. The tech giant's new ...

Asia Times

SUMMARY

**Automate Your Hi-Mix Die Attach**

MAT 6200 Crossover, low cost, entry level auto Die-Attach ideal for low volume Prototypes, NPI, CMS environments. Easy GUI Set-up, Rapid turnover, Multi-Process support.

**MicroAssembly Technologies**

**Automatic Grading Without Assistance**

Eliminate the need for operators to assess bond testing failure modes at the end of an automation run. Auto grading uses machine vision software to process the test result images.

**xyztec**

**[China grants first generative AI model for download to play catchup](#)**

China introduces "Ernie Bot," a cutting-edge generative AI software powered by big data. Ernie Bot's launch ...

Digitimes

SUMMARY

**Improve Your Advanced Package Fault Isolation**

**PROVEN**  
Ultra-Low Residue Ball-Attach and Flip-Chip Flux

**NC-809**

**PACKAGING SOLUTIONS**

Permanent Bonding Materials for low-temperature bonding, excellent chemical resistance, thermally curable bonding process and no material movement after the bonding process

**Quote of the Day**

I believe that freedom is the deepest need of every human soul.

George W. Bush

**Fusion and Hybrid Bonding Experts**

EVG's industry-leading process solutions, expertise and HI Competence Center accelerate the development and implementation of heterogeneous integration technology.

EV Group



**Essential Inspection Requirements in the Era of Convergence**

Herein, learn ways to optimize processes and boost quality as advanced packages and board assembly converge.

Read more.

Koh Young America, Inc.



**What Year Was It?**

**Atlanta Falls to Union Forces**

Union Army General William Tecumseh Sherman lays siege to Atlanta, Georgia, a critical Confederate hub, shelling civilians and cutting off supply lines.



The day was Sep 1. What year was it?

**Improved Wire Bond Reliability**

Auxiliary wires are commonly defined as an additional wire outside of a normal ball-to-stitch wire bond. The motivation behind using auxiliary wires is the inherent weakness of the stitch bond.

Palomar Technologies, Inc.



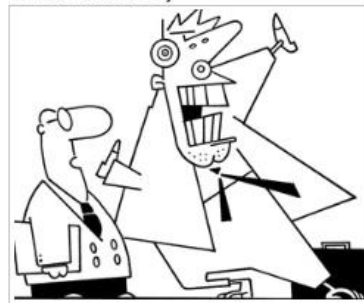
**Alternatives to Isopropyl Alcohol (IPA)**

Having a hard time finding IPA? KYZEN offers safe, affordable alternatives globally! To learn more, fill out this form to download our technical brief!

KYZEN



**Cartoon of the Day**



"I'd like to apologize for asking you to step outside of your comfort zone."

Copyright © Randy Glasbergen



### Calendar

- [Sep 5, 2023: Advanced Packaging Summit 2023](#)
- [Sep 6, 2023: SEMICON Taiwan 2023](#)
- [Sep 6, 2023: Overview of semiconductor manufacturing for European Attendees](#)
- [Sep 7, 2023: EH&S Japan TC Chapter Meeting](#)

#### Automate Your Hi-Mix Die Attach

MAT 6200 Crossover, low cost, entry level auto Die-Attach ideal for low volume Prototypes, NPI, CMS environments. Easy GUI Set-up, Rapid turnover, Multi-Process support.  
**MicroAssembly Technologies**



#### Automatic Grading Without Assistance

Eliminate the need for operators to assess bond testing failure modes at the end of an automation run. Auto grading uses machine vision software to process the test result images.  
**xyztec**



#### 3D chip stacking, hybridization services

ARC provides: • turnkey, 3D Chip Stacking & Hybridization Services. • Wafer Bumping to Completed Chip Stack at ARC. • Wire bonding of die stacks, all in-house. • ISO|ITAR.  
**ARC**



#### Test Your Knowledge Answer

What line on a map connects all points of the same elevation?  
 Answer: A contour line

[NEWSLETTER ARCHIVES](#)

[About Us](#) | [Advertising](#) | [Archives](#) | [Calendar](#) | [Contact Us](#) | [Custom Email Broadcast](#) | [Disclaimer](#) | [Exclusives](#) | [News](#) | [Press Releases](#) | [Press Release Submit](#) | [Privacy Policy](#) | [Search](#) | [Subscription](#) | [Viewpoint](#) | [White Papers](#) | [White Paper Submit](#)

#### Circuitnet Media, LLC

6 Liberty Square #2040, Boston MA 02109 USA

Jeff Ferry, Publisher | Ken Cavallaro, Editor/Business Manager

Copyright © Circuitnet Media LLC. All rights reserved.

[A Circuitnet Media Publication](#)

ISSN 2768-2706

This email was sent to [dmoreno@openskypr.com](mailto:dmoreno@openskypr.com) - [Unsubscribe](#)  
[Add us to your address book](#)